

SKiiP 11AC12T7V1



MiniSKiiP® 1

Sixpack

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Features*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

Remarks

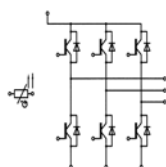
- Max. case temperature limited to $T_C = T_S = 125^\circ\text{C}$
- Product reliability results valid for $T_j \leq 150^\circ\text{C}$ (recommended $T_{j,op} = -40 \dots +150^\circ\text{C}$)
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Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 70 °C	20	A
	T _j = 175 °C	T _s = 100 °C	16	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 70 °C	21	A
	T _j = 175 °C	T _s = 100 °C	18	A
I _{Cnom}			10	A
I _{CRM}			20	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 175 °C	7	μs
T _j			-40 ... 175	°C
Inverse - Diode				
I _F	λ _{paste} =0.8 W/(mK)	T _s = 70 °C	13	A
	T _j = 175 °C	T _s = 100 °C	11	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 70 °C	14	A
	T _j = 175 °C	T _s = 100 °C	12	A
I _{FRM}			16	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 150 °C		36	A
T _j			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C, 20 A per spring		40	A
T _{stg}	module without TIM		-40 ... 125	°C
V _{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Inverter - IGBT					
$V_{CE(sat)}$	$I_C = 10 \text{ A}$	$T_j = 25^\circ\text{C}$	1.60	1.75	V
	$V_{GE} = 15 \text{ V}$	$T_j = 150^\circ\text{C}$	1.82	1.96	V
	chiplevel	$T_j = 175^\circ\text{C}$	1.86	2.00	V
V_{CE0}		$T_j = 25^\circ\text{C}$	0.90	1.00	V
	chiplevel	$T_j = 150^\circ\text{C}$	0.75	0.83	V
		$T_j = 175^\circ\text{C}$	0.72	0.80	V
r_{CE}	$V_{GE} = 15 \text{ V}$	$T_j = 25^\circ\text{C}$	70	75	$\text{m}\Omega$
	chiplevel	$T_j = 150^\circ\text{C}$	107	113	$\text{m}\Omega$
		$T_j = 175^\circ\text{C}$	114	120	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 0.22 \text{ mA}$	5.15	5.8	6.45	V
I_{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}, T_j = 25^\circ\text{C}$			1	mA
C_{ies}	$V_{CE} = 25 \text{ V}$	$f = 1 \text{ MHz}$	1.90		nF
C_{oes}	$V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$	0.02		nF
C_{res}		$f = 1 \text{ MHz}$	0.01		nF
Q_G	$V_{GE} = -8 \text{ V} \dots +15 \text{ V}$		140		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		0		Ω



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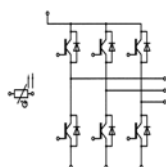
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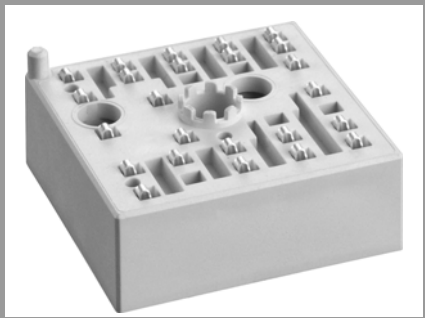


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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
t _{d(on)}	V _{CC} = 600 V I _C = 10 A R _{G on} = 32 Ω R _{G off} = 32 Ω V _{GE} = +15/-15 V @ T _j = 150 °C: di/dt _{on} = 190 A/μs di/dt _{off} = 130 A/μs dv/dt = 3580 V/μs	T _j = 25 °C		44		ns
		T _j = 150 °C		46		ns
		T _j = 175 °C		47		ns
t _r		T _j = 25 °C		39		ns
		T _j = 150 °C		44		ns
		T _j = 175 °C		47		ns
E _{on}		T _j = 25 °C		0.88		mJ
		T _j = 150 °C		1.2		mJ
		T _j = 175 °C		1.3		mJ
t _{d(off)}		T _j = 25 °C		198		ns
		T _j = 150 °C		288		ns
		T _j = 175 °C		313		ns
t _f		T _j = 25 °C		42		ns
		T _j = 150 °C		63		ns
		T _j = 175 °C		85		ns
E _{off}		T _j = 25 °C		0.65		mJ
	T _j = 150 °C		1.1		mJ	
	T _j = 175 °C		1.2		mJ	
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)			1.7		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			1.46		K/W

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
V _F = V _{EC}	I _F = 10 A	T _j = 25 °C		2.59	2.94	V
	V _{GE} = 0 V	T _j = 150 °C		2.71	3.08	V
	chipelevel	T _j = 175 °C		2.53	2.89	V
V _{F0}	chipelevel	T _j = 25 °C		1.30	1.50	V
		T _j = 150 °C		0.90	1.10	V
		T _j = 175 °C		0.82	0.98	V
r _F	chipelevel	T _j = 25 °C		129	144	mΩ
		T _j = 150 °C		181	198	mΩ
		T _j = 175 °C		171	191	mΩ
I _{RRM}	I _F = 10 A V _{GE} = +15/-15 V V _{CC} = 600 V	T _j = 25 °C		6		A
		T _j = 150 °C		7		A
		T _j = 175 °C		8		A
Q _{rr}		T _j = 25 °C		0.7		μC
		T _j = 150 °C		1.4		μC
		T _j = 175 °C		1.6		μC
E _{rr}	@ T _j = 150 °C: di/dt _{off} = 210 A/μs	T _j = 25 °C		0.19		mJ
		T _j = 150 °C		0.53		mJ
		T _j = 175 °C		0.69		mJ
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			2.33		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			2		K/W
Module						
L _{CE}				-		nH
M _s	to heat sink		2		2.5	Nm
w				30		g

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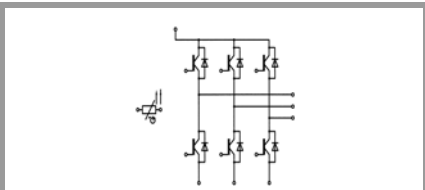
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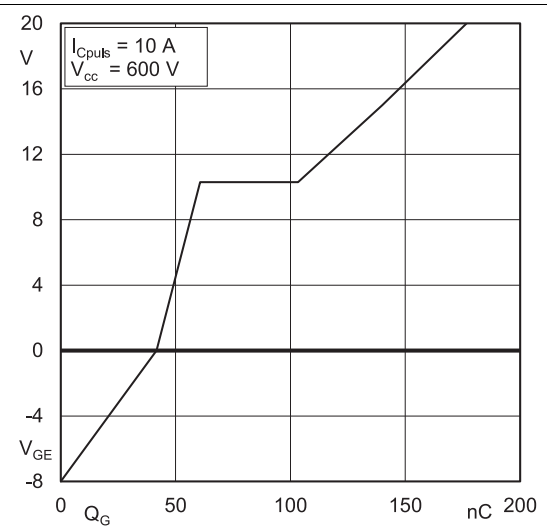
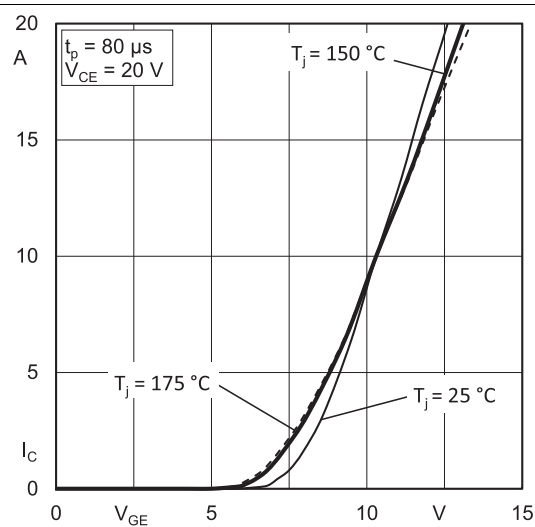
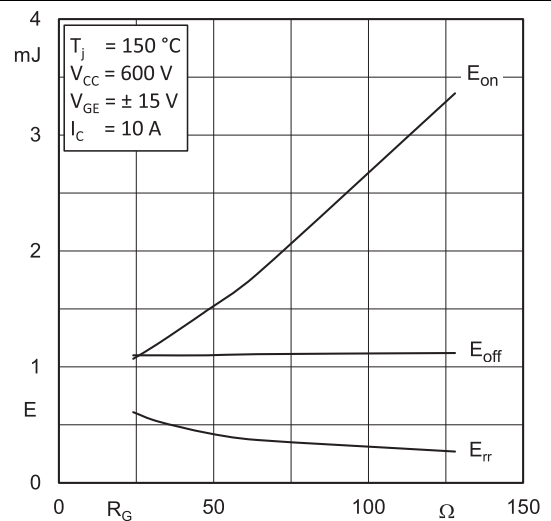
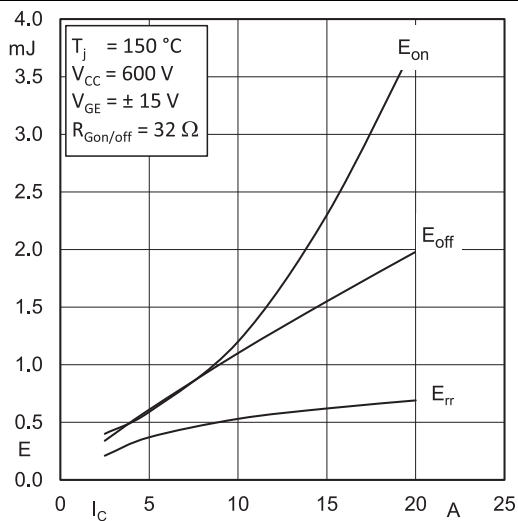
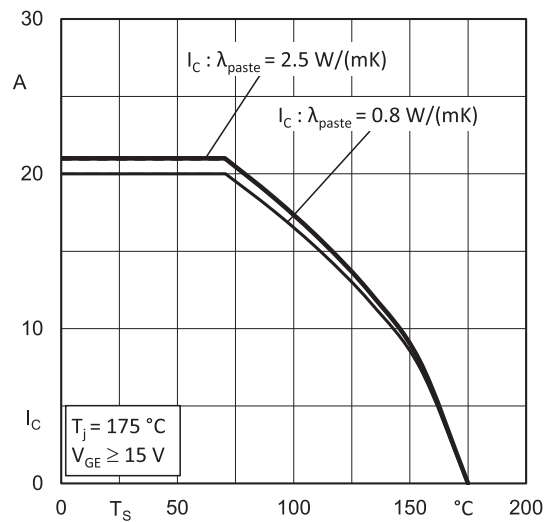
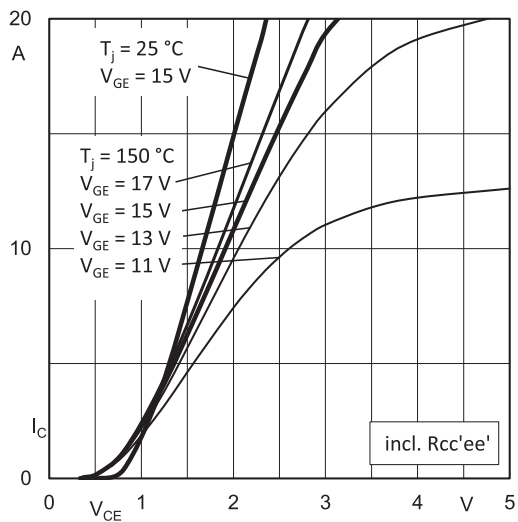
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Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
Temperature Sensor					
R_{100}	$T_f=100\text{ °C}$ ($R_{25}=1000\Omega$)		$1670 \pm 3\%$		Ω
$R_{(T)}$	$R_{(T)}=1000\Omega[1+A(T-25\text{ °C})+B(T-25\text{ °C})^2]$, $A = 7.635\cdot 10^{-3}\text{ °C}^{-1}$, $B = 1.731\cdot 10^{-5}\text{ °C}^{-2}$				

Creepage distance (spring to spring) between temperature sensor and phase W = 2.9mm (CTI 600)



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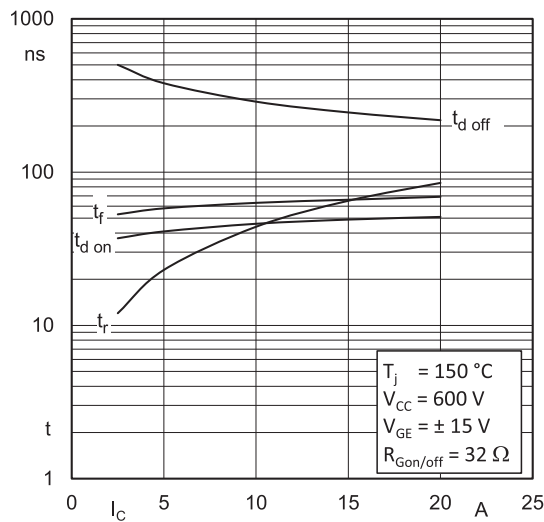


Fig. 7: Typ. switching times vs. I_C

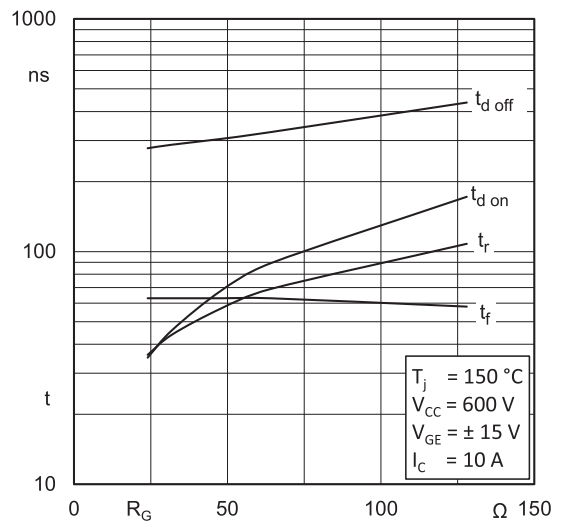


Fig. 8: Typ. switching times vs. gate resistor R_G

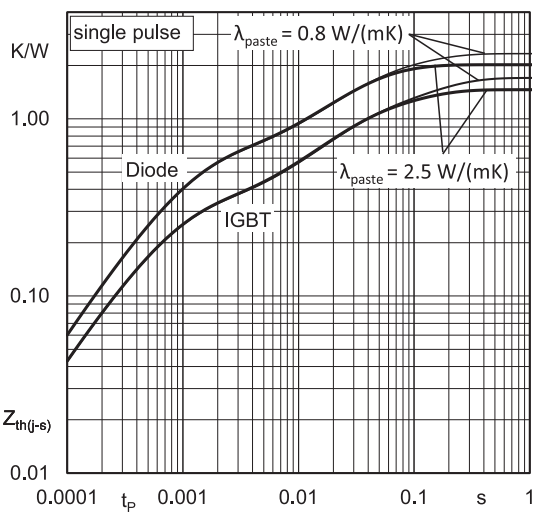


Fig. 9: Transient thermal impedance

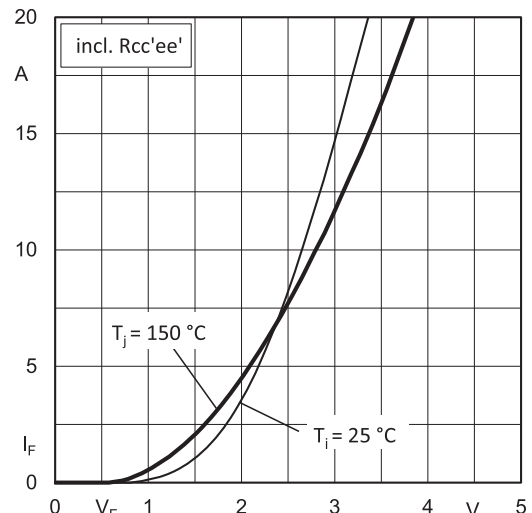


Fig. 10: Typ. CAL diode forward characteristic

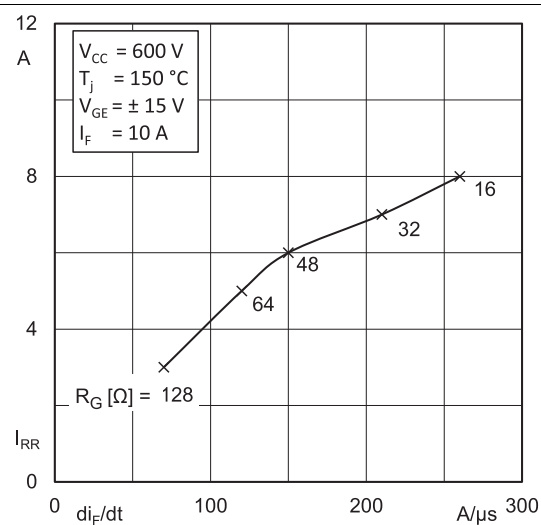


Fig. 11: Typ. CAL diode peak reverse recovery current

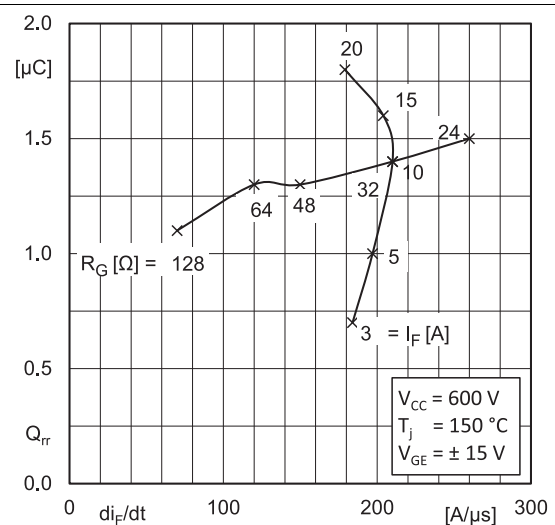
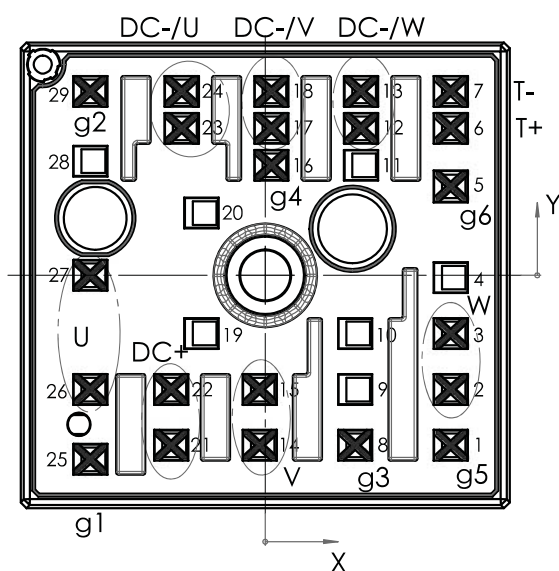


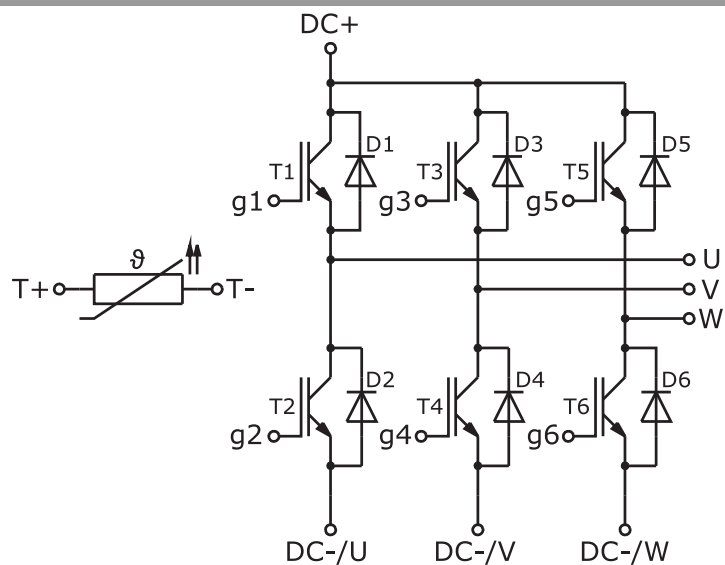
Fig. 12: Typ. CAL diode recovery charge

Pin out							
Pin	X	Y	Function	Pin	X	Y	Function
1	15,93	-14,6	g5	16	0,53	9,45	g4
2	15,93	-9,8	W	17	0,53	12,63	DC-/V
3	15,93	-5	W	18	0,53	15,8	DC-/V
4				19			
5	15,93	7,63	g6	20			
6	15,93	12,63	T+	21	-8,08	-14,6	DC+
7	15,93	15,8	T-	22	-8,08	-9,8	DC+
8	7,73	-14,6	g3	23	-7,18	12,63	DC-/U
9	7,73	-9,8		24	-7,18	15,8	DC-/U
10				25	-15,03	-15,8	g1
11				26	-15,03	-9,8	U
12	8,23	12,63	DC-/W	27	-15,03	0	U
13	8,23	15,8	DC-/W	28			
14	-0,48	-14,6	V	29	-15,03	15,8	g2
15	-0,48	-9,8	V				

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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